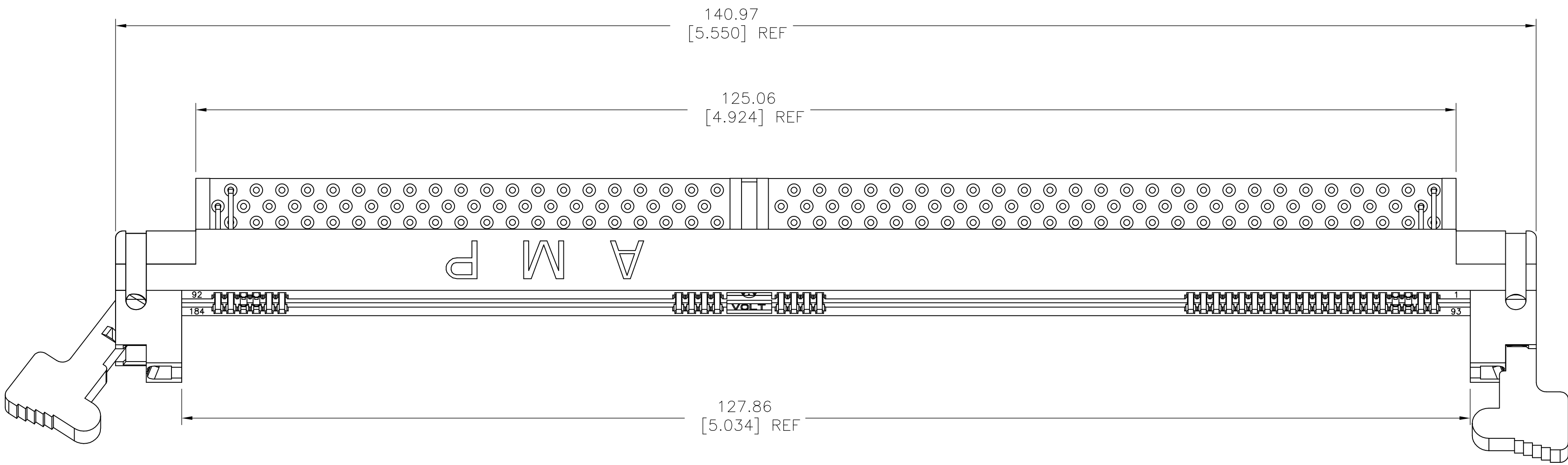


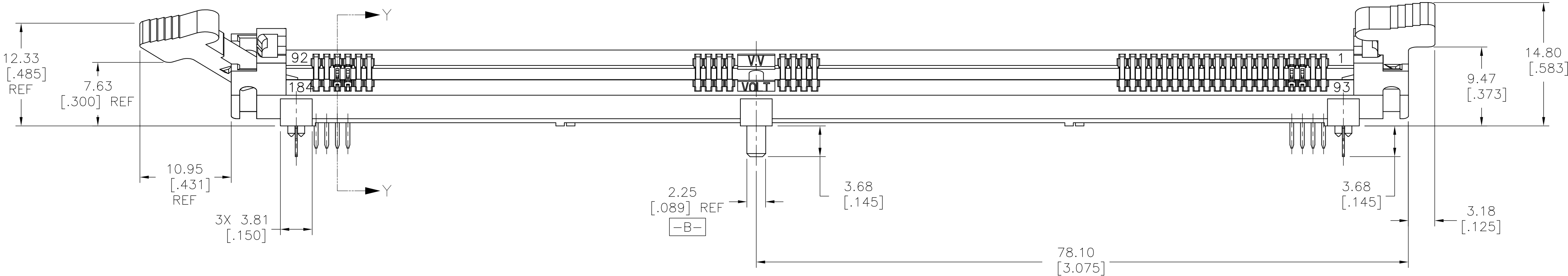
LOC	DIST	REVISONS				
		FR	LTR	DESCRIPTION	DATE	DWN
GP	00	A		REVISED PER EC OS11-0009-05	08APR05	BM
		A1		REVISED PER ECO-10-000444	04NOV09	KK

1. MATERIAL:
HOUSING AND EJECTOR:
HIGH TEMPERATURE NYLON
CONTACT:
PHOSPHOR BRONZE
2. FINISH:
CONTACT AREA:
0.000760[.000030] MIN GOLD OVER
0.001270[.000050] MIN THICK NICKEL
SOLDER TAIL:
0.00381[.000150] MIN THICK MATTE TIN OVER
0.00064[.000025] MIN THICK NICKEL
3. MODULE BOARD PADS:
FOR OPTIMUM PERFORMANCE PADS SHOULD BE SMOOTH AND FLAT
PADS TO BE PLATED WITH:
0.00102[.000040] MIN THICK GOLD OVER
0.00127[.000050] MIN THICK NICKEL
4. PN: 5390402-6 IS THE SAME CONNECTOR AS 5390402-3
WITH LUBRICANT ADDED TO THE CONTACTS.
5. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

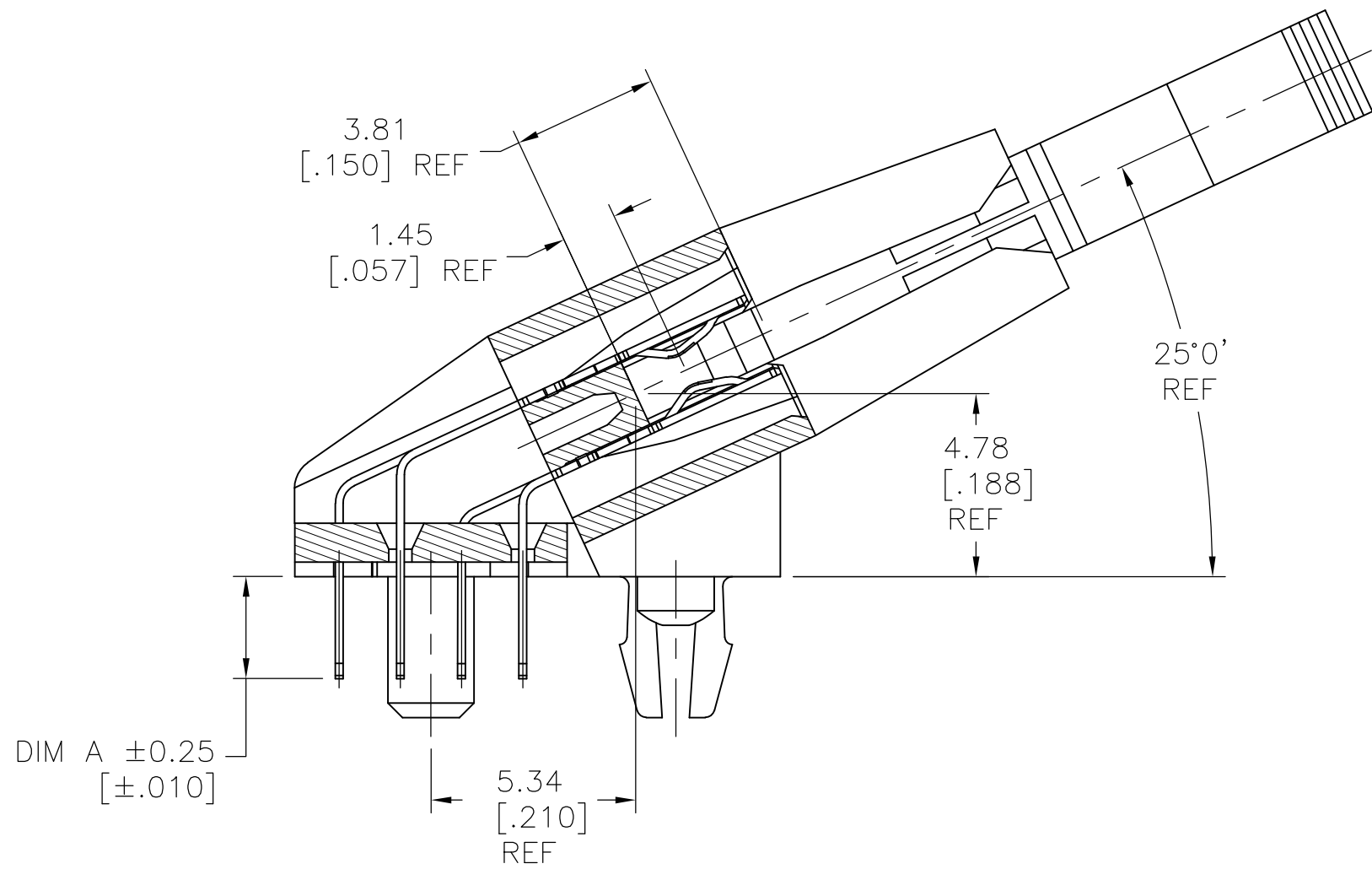
D



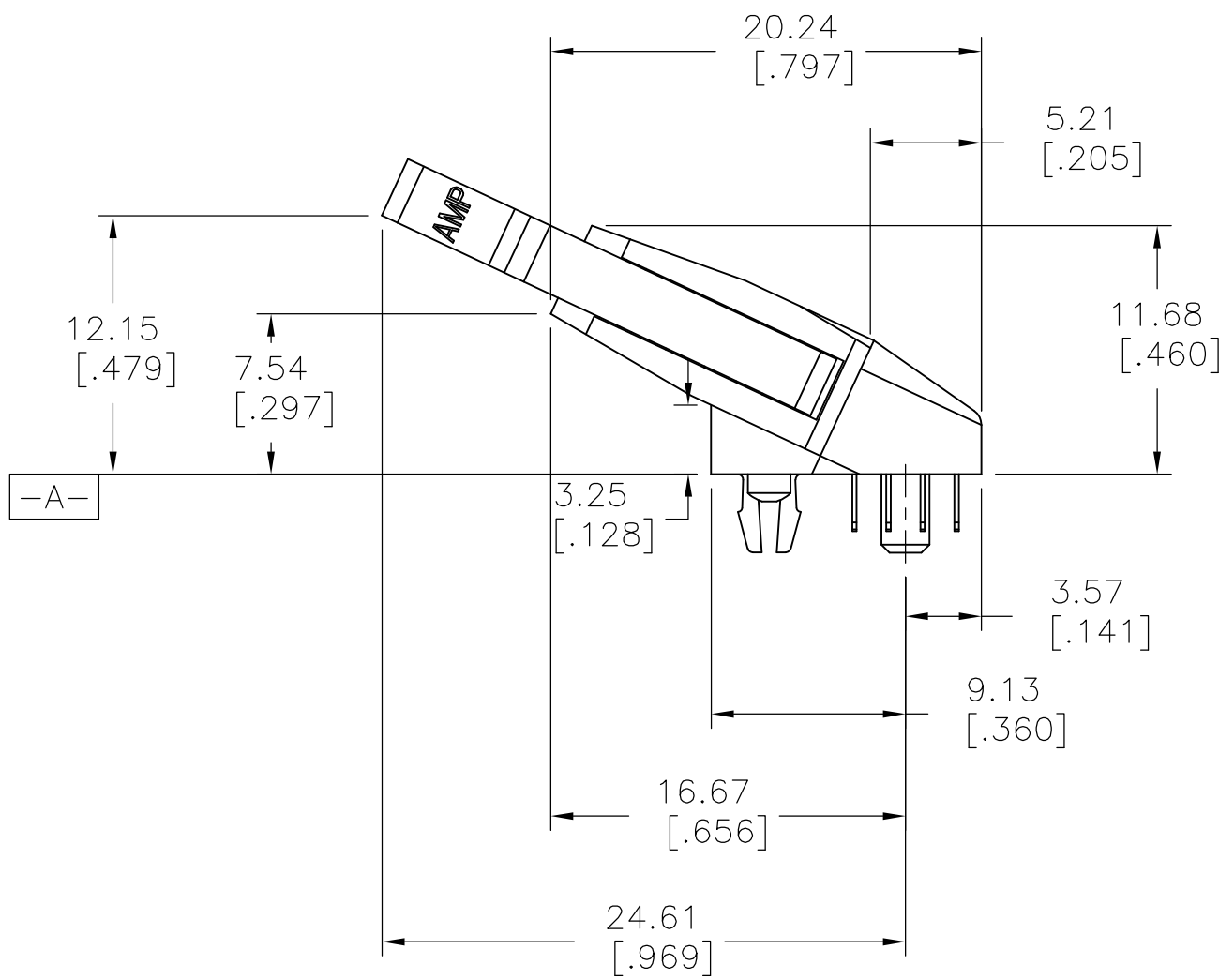
C



B



SECTION Y-Y
SCALE 6:1



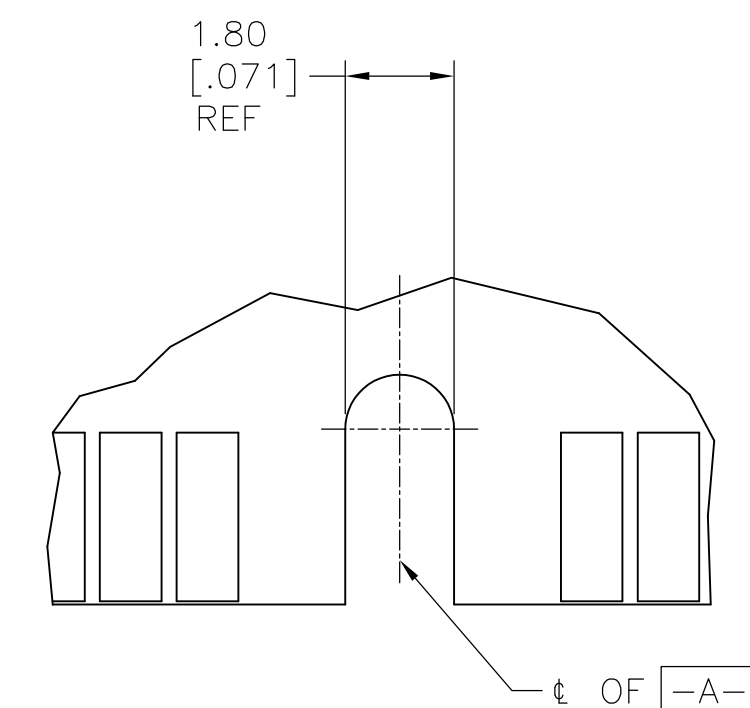
C

B

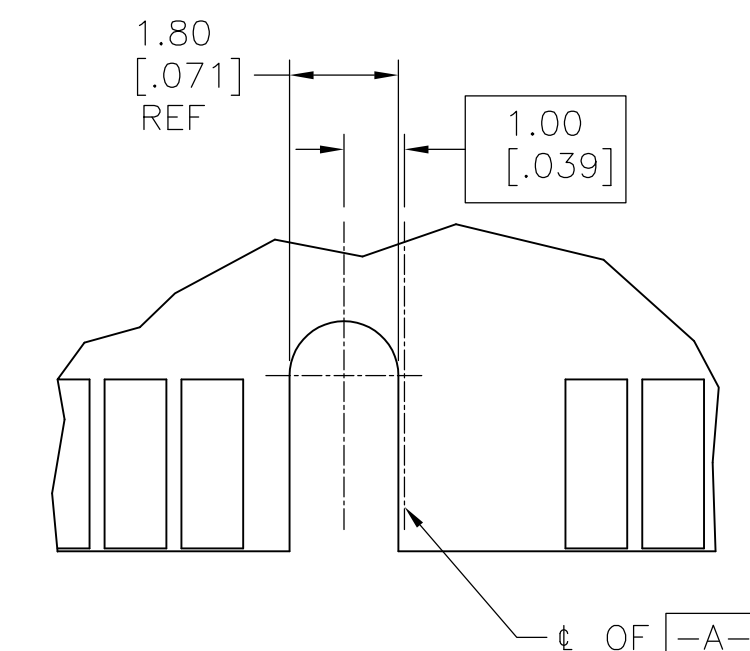
A

5 OBSOLETE	4.50 [.177]	DETAIL B	184 POSN. DDR, 2.5V	5390402-7
	3.18 [.125]	DETAIL B	184 POSN. DDR, 2.5V	5390402-6 4
	3.18 [.125]	DETAIL A	184 POSN. DDR, 1.8V	5390402-4
5 OBSOLETE	3.18 [.125]	DETAIL B	184 POSN. DDR, 2.5V	5390402-3
	2.62 [.103]	DETAIL A	184 POSN. DDR, 1.8V	5390402-2
	2.62 [.103]	DETAIL B	184 POSN. DDR, 2.5V	5390402-1
DIM A		KEY POSITIONS	DESCRIPTION	PART NUMBER

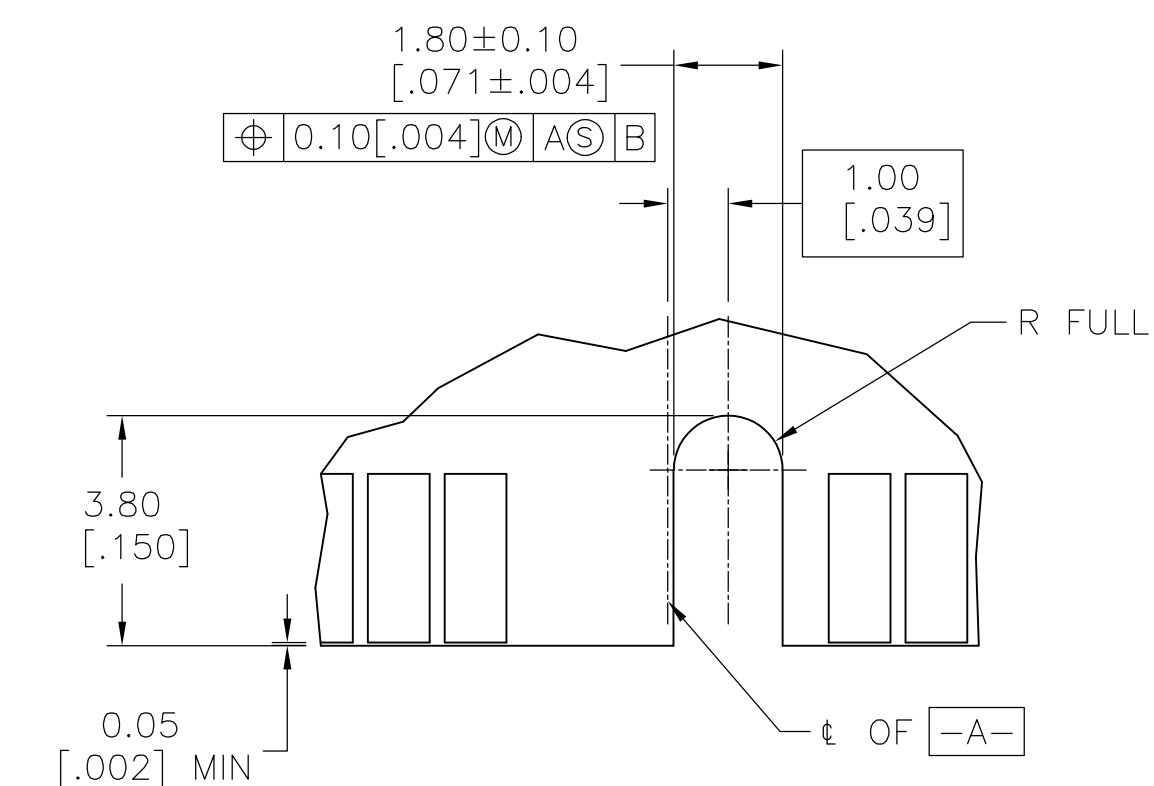
THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN S.WAITMAN 11OCT04	Tyco Electronics Corporation Harriaburg, Pa 17105-3608	
DIMENSIONS: mm		CHK M.YEOMANS 11OCT04	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPROD M.YEOMANS 11OCT04	PRODUCT SPEC	
0 PLC ± -		APPLICATION SPEC		SIZE
1 PLC ± -		WEIGHT		CAGE CODE
2 PLC ± 0.13[.005]		DRAWING NO		RESTRICTED TO
3 PLC ± -		A100779		REV
4 PLC ± -		5390402		
ANGLES ± -		CUSTOMER DRAWING		SCALE
FINISH		3:1		SHEET
1		1 OF 3		REV



DETAIL A
SCALE 8:1

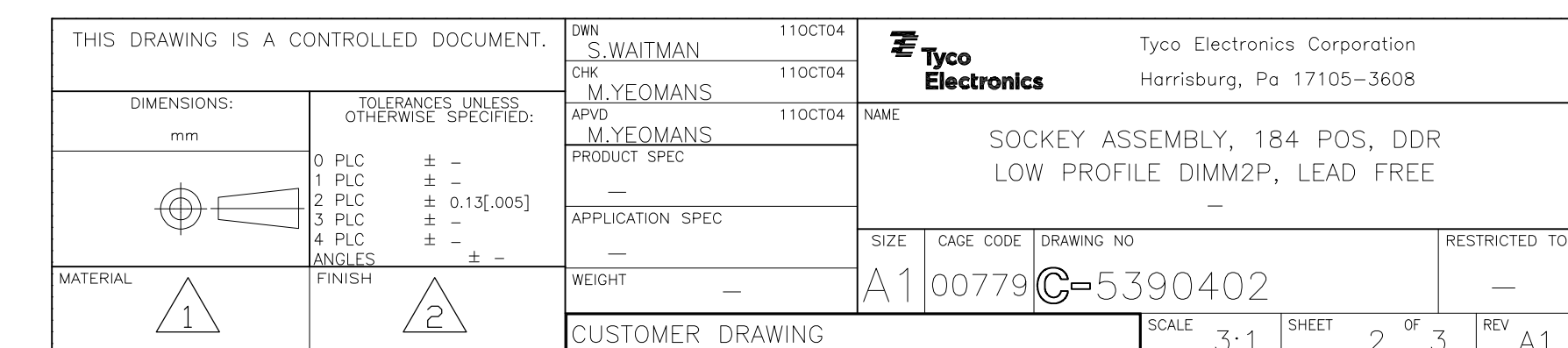


DETAIL B
SCALE 8:1



DETAIL C
SCALE 8:1

KEY POSITIONS

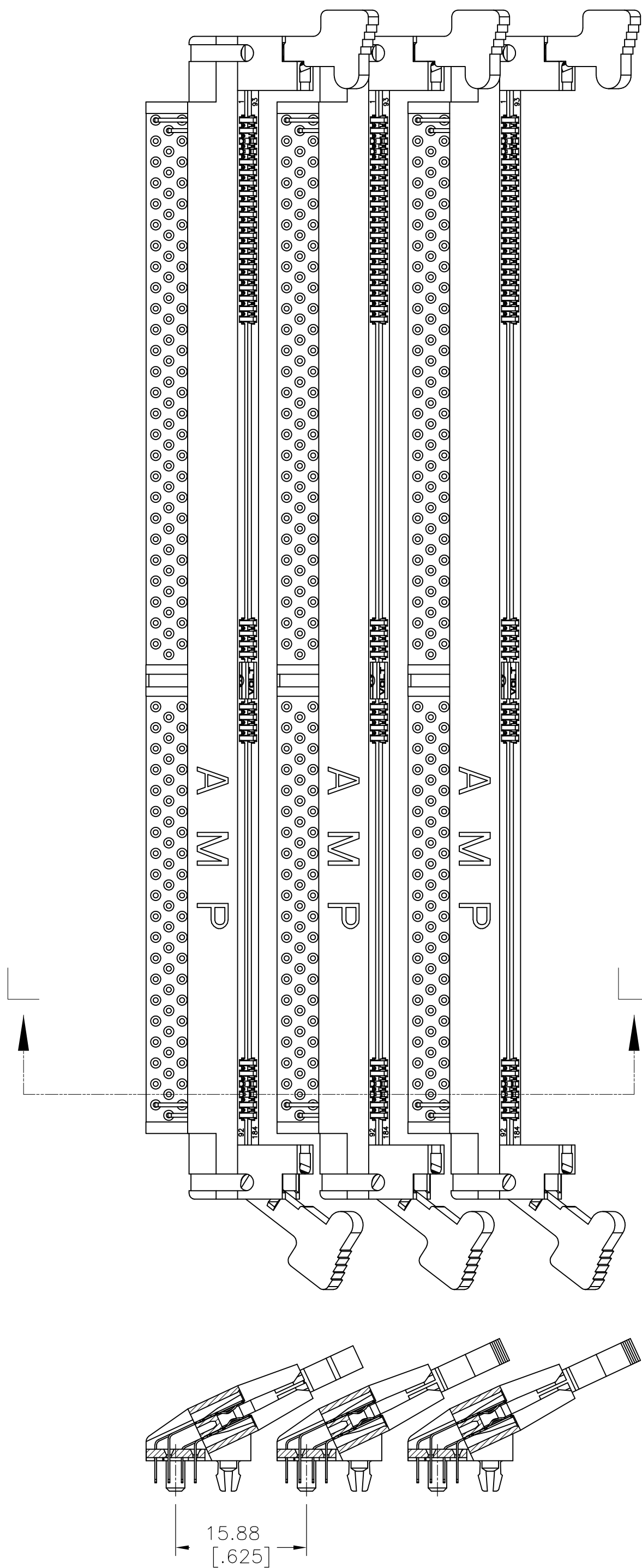


D

C

B

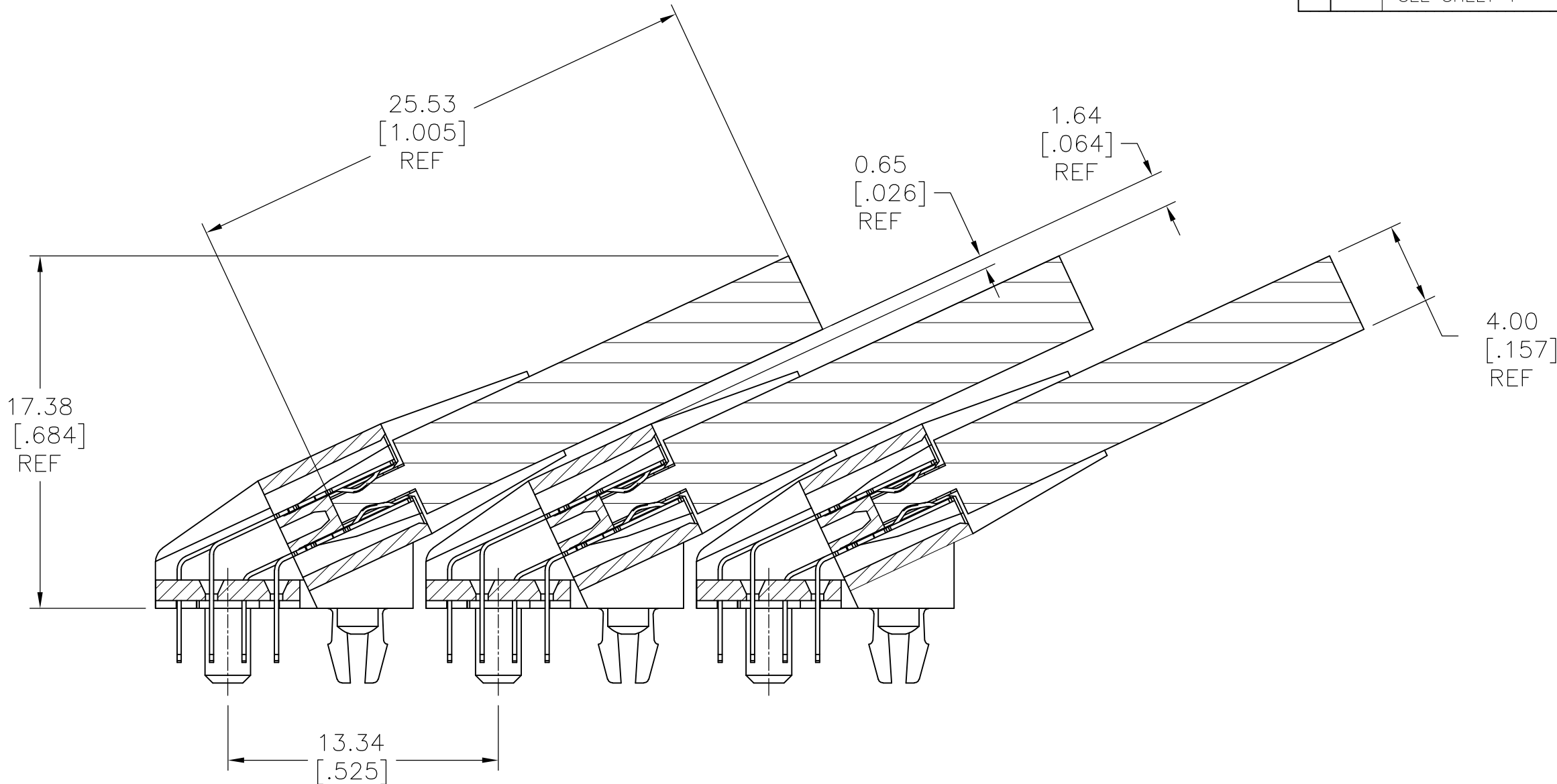
A



SECTION L-L
SCALE 2:1

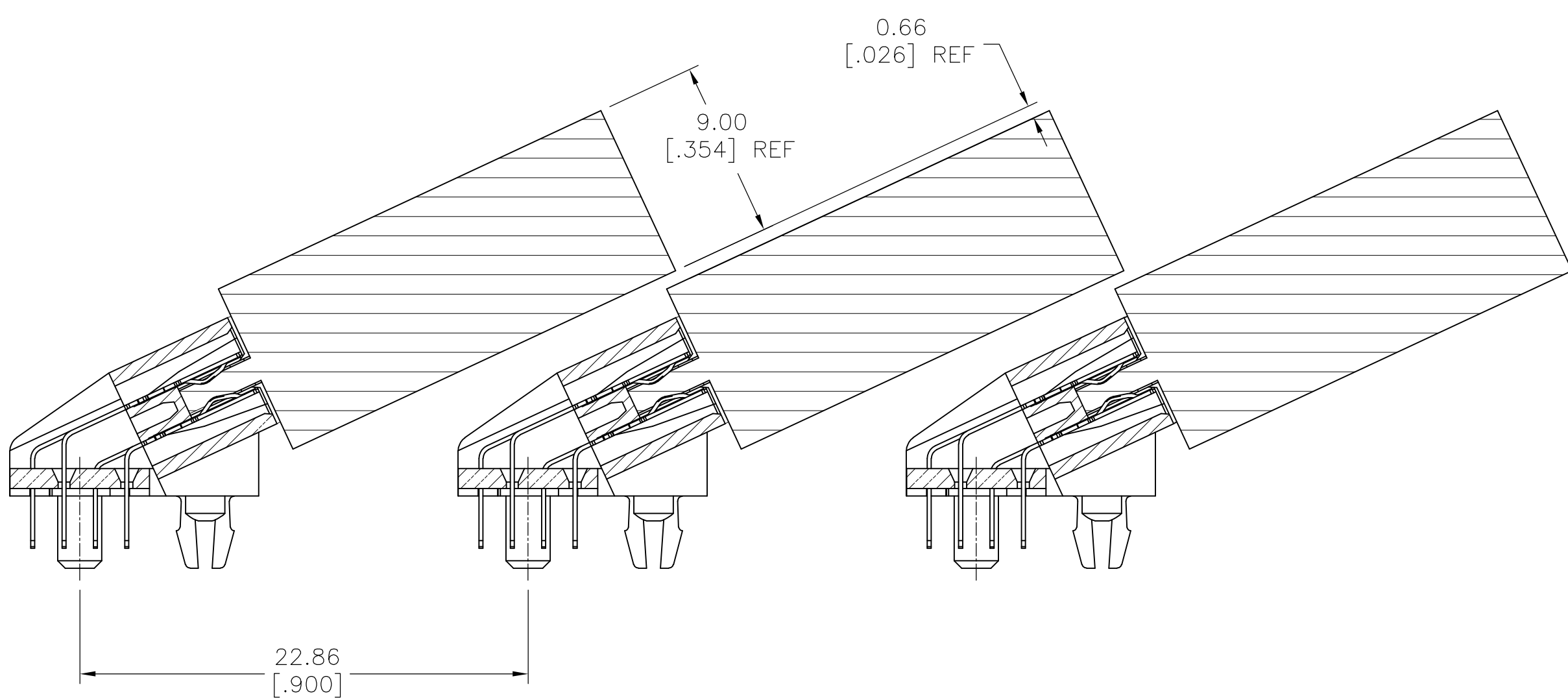
MINIMUM REPAIRABLE
SOCKET TO SOCKET REPAIRING

WITH THE MODULES REMOVED SOCKETS ON 15.88[.625]
OR GREATER SPACING CAN BE INDIVIDUALLY UNSOLDERED
FROM THE BOARD AND REMOVED IF NECESSARY



MINIMUM SOCKET TO SOCKET SPACING

WITH A 4.00[.158] WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34[.525] WILL LEAVE APPROXIMATELY 0.65[.026] OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMNETS.



POSSIBLE SOCKET TO SOCKET SPACING FOR 9MM MODULE

WITH A 9.00[.355] WIDE MODULE BOARD; A SOCKET TO SOCKET SPACING OF 22.86[.900] WILL LEAVE APPROXIMATELY 0.66[.026] CLEARANCE BETWEEN THE ADJACENT MODULES. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.

Mouser Electronics

Authorized Distributor

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[TE Connectivity:](#)

[5390402-1](#)